

IN THE CLAIMS:

Please amend the claims as follows:

1-12. *(canceled)*

13. *(currently amended)* A mobile phone comprising a system for analysing connection conditions between an integrated circuit package and a circuit board, said system comprising:

- coupling elements coupling said integrated circuit package electrically to said circuit board, and
- support elements directly connecting said integrated circuit package mechanically with said circuit board using solder balls, ~~wherein said system further comprises:~~
 - means for conductors configured to electrically ~~connecting~~ connect at least two of said support elements with each other on the side of the integrated circuit package,
 - measuring means arranged at said support elements ~~for picking-off and configured to pick-off~~ physical values between said support elements, and
 - evaluation means ~~for evaluating~~ configured to evaluate said physical values to determine mechanical properties of said support elements, and ~~for concluding configured to conclude~~ a condition of said electrical coupling of said integrated circuit package with said circuit board from said determined mechanical properties of said support elements.

14. *(currently amended)* The system mobile phone of claim 13, wherein said support elements are arranged between said circuit board and said integrated circuit package.

15. *(currently amended)* The system mobile phone of claim 13, wherein said support elements are solder pads.
16. *(currently amended)* The system mobile phone of claim 13, wherein said support elements are arranged adjacent to said coupling elements.
17. *(currently amended)* The system mobile phone of claim 13, wherein said support elements are arranged semicircular along said coupling elements.
18. *(currently amended)* The system mobile phone of claim 13, wherein said support elements are arranged along edges and/or at corners of said integrated circuit package.
19. *(currently amended)* The system mobile phone of claim 13, wherein said integrated circuit package is a chip scale package or a chip size package.
20. *(currently amended)* The system mobile phone claim 13, wherein said measuring means provide picking-off electrical conditions of said support elements.
21. *(currently amended)* The system mobile phone claim 13, wherein said measuring means provide picking-off mechanical conditions of said support elements.
22. *(currently amended)* The system mobile phone of claim 13, wherein storage means are comprised to store said picked-off physical values.

23. *(currently amended)* The system mobile phone of claim 13, wherein said evaluation means compare said picked-off physical values with comparative values to determine connection condition.
24. *(currently amended)* The system mobile phone of claim 13, wherein said evaluation means provide an error message in case a poor connection condition is determined.
25. *(currently amended)* The system mobile phone of claim 13, wherein said error message is stored within said storage means.
26. *(currently amended)* The system mobile phone of claim 13, wherein an interface is provided to read out said stored physical values and/or stored error messages.
- 27-29. *(canceled)*
30. *(new)* An apparatus comprising:
 - coupling elements coupling an integrated circuit package electrically to a circuit board,
 - support elements directly connecting said integrated circuit package mechanically with said circuit board using solder balls,
 - conductors configured to electrically connect at least two of said support elements with each other on the side of the integrated circuit package,
 - measuring means arranged at said support elements and configured to pick-off physical values between said support elements, and
 - evaluation means configured to evaluate said physical values to determine mechanical properties of said support elements, and configured to conclude a condition of said electrical coupling of said integrated circuit package with said

circuit board from said determined mechanical properties of said support elements.

31. (new) The system of claim 30, wherein said support elements are arranged semicircular along said coupling elements.
32. (new) The apparatus of claim 30, wherein said support elements are arranged along edges and/or at corners of said integrated circuit package.
33. (new) An apparatus comprising:
 - coupling elements coupling an integrated circuit package electrically to a circuit board, and
 - support elements directly connecting said integrated circuit package mechanically with said circuit board using solder balls,
 - means for electrically connecting at least two of said support elements with each other on the side of the integrated circuit package,
 - measuring means arranged at said support elements for picking off physical values between said support elements, and
 - evaluation means for evaluating said physical values to determine mechanical properties of said support elements, and for concluding a condition of said electrical coupling of said integrated circuit package with said circuit board from said determined mechanical properties of said support elements.
34. (new) The apparatus of claim 33, wherein said support elements are arranged semicircular along said coupling elements.